

Implementation of an Open-Source modular magnetic field camera hardware for usage in Low-Field MRI Systems

1st Marcel Werner Heinrich Friedrich Ochsendorf

Fachhochschule Aachen

Electrical Engineering and Information Technology

Aachen, Deutschland

marcelochsendorf@alumni.fh-aachen.de

Name	Range (mT)
Honeywell HMC5883L	1.3 - 8.1 mT
STMicroelectronics LIS3MDL	4 - 16 mT
TDK InvenSense ICM-20948	49 mT

Tabelle I

IMPLEMENTED 3D MAGNETOMETER ICS

In this way, an 8x8 sensor array can be built quickly, and the mechanical stability and alignment is ensured by the interconnection of the golf finger pads.

Zusammenfassung— Index Terms—

I. INTRODUCTION

A. Use Cases

II. HARDWARE

A. Sensor selection

B. Sensor slice

Each sensor slice has its own microprocessor as a communication element. this takes over the task of reading the connected sensors and transmitting the results via the system bus. The interfaces for different sensor types are also implemented in its firmware. this makes it possible to mix different sensor types on one slice. the slice presents itself to the rest of the system as a uniform sensor with a uniform measurement result. For this purpose, calibration and unit conversions are automatically applied in the firmware of the slice, depending on which sensor has been detected.

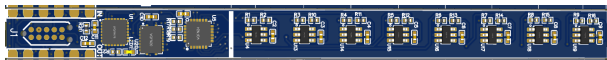


Abbildung 1. Sensor Slice with eight TLV493d sensors

The sensor slice shown in Figure ?? consists of 8 TLV493d sensors spaced 8mm apart on an 8mm x 64mm PCB. To build a larger sensor array, the golf finger pads of the board can be soldered to other similar boards in a daisy chain configuration.

The daisy chain design simplifies connectivity as multiple slices can be connected in a linear fashion, reducing complex wiring. This approach simplifies expansion and troubleshooting, as new slices can be easily added or removed without disrupting the entire system.

C. Communication bus

To ensure modularity and easy expandability of the sensor system, it is necessary to be able to integrate several sensor slices into the system. On the electrical level, a CAN bus was implemented to connect the individual microprocessors to which up to 16 magnetic field sensors can be digitally connected to an overall system.

In addition to the bus system, a supply voltage and a separate synchronisation signal are necessary to enable automatic recognition of connected sensors. This is connected in a daisy chain between the slices. This enables the microcontroller of a sensor slice to recognise whether it is integrated into a network and to register itself via the system bus.

D. Powermanagement

Each sensor slice also implements its own power management of the sensors, both at the hardware and software level, but this is optional.

Depending on the type of sensor used, the current flowing through the individual layers can influence its measurement result. Therefore, the control logic and voltage converter components were placed separately from the sensors in the board layout. In addition, individual sensors can be specifically supplied with voltage. This was implemented using a switchable power supply (PCF847). The software is later (when activated) able to activate only the sensor that is to be read out at the current time. A disadvantage of this implementation, however, is that each sensor must be reconfigured after activating the power supply. Depending on the selected sensor, this can take up to an additional 10ms per sensor measurement.

- [1] Marcel Ochsendorf: Development of a hardware and software framework for the automated characterization of permanent magnets for low-field MRI systems. Available: https://www.researchgate.net/publication/374388764_Development_of_a_permanent_magnet_characterization_framework_for_use_in_low-field_MRI_systems, 17.11.2021.
- [2] Marcel Ochsendorf: MagneticReadoutProcessingFramework. <https://github.com/LFB-MRI/MagneticReadoutProcessing>, 17.11.2021